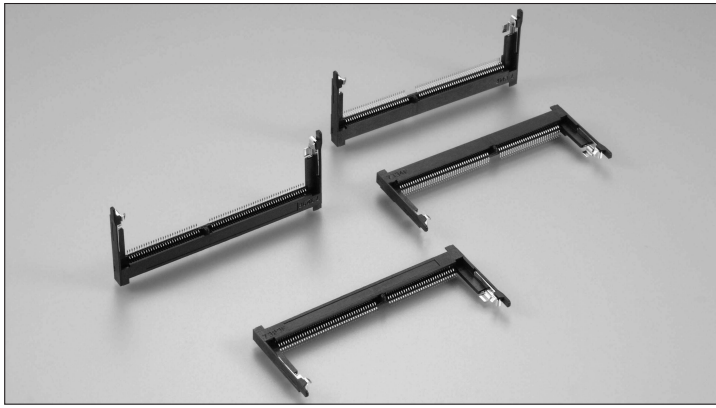


DM03/04 SERIES conforms to JEDEC standards
SMALL OUTLINE DUAL INLINE MEMORY MODULE SOCKET

DM03/04 SERIES





FEATURES

- DM03/04 SERIES conforms to JEDEC standards
- Memory Module Board is retained in the socket by metal latches.
- Easy insertion and withdrawal of Memory Module Board
- Metal latches are highly reliable.
- TSOP DRAM or other components can be mounted beneath DM03/04 socket
- RoHS compliance

SPECIFICATIONS

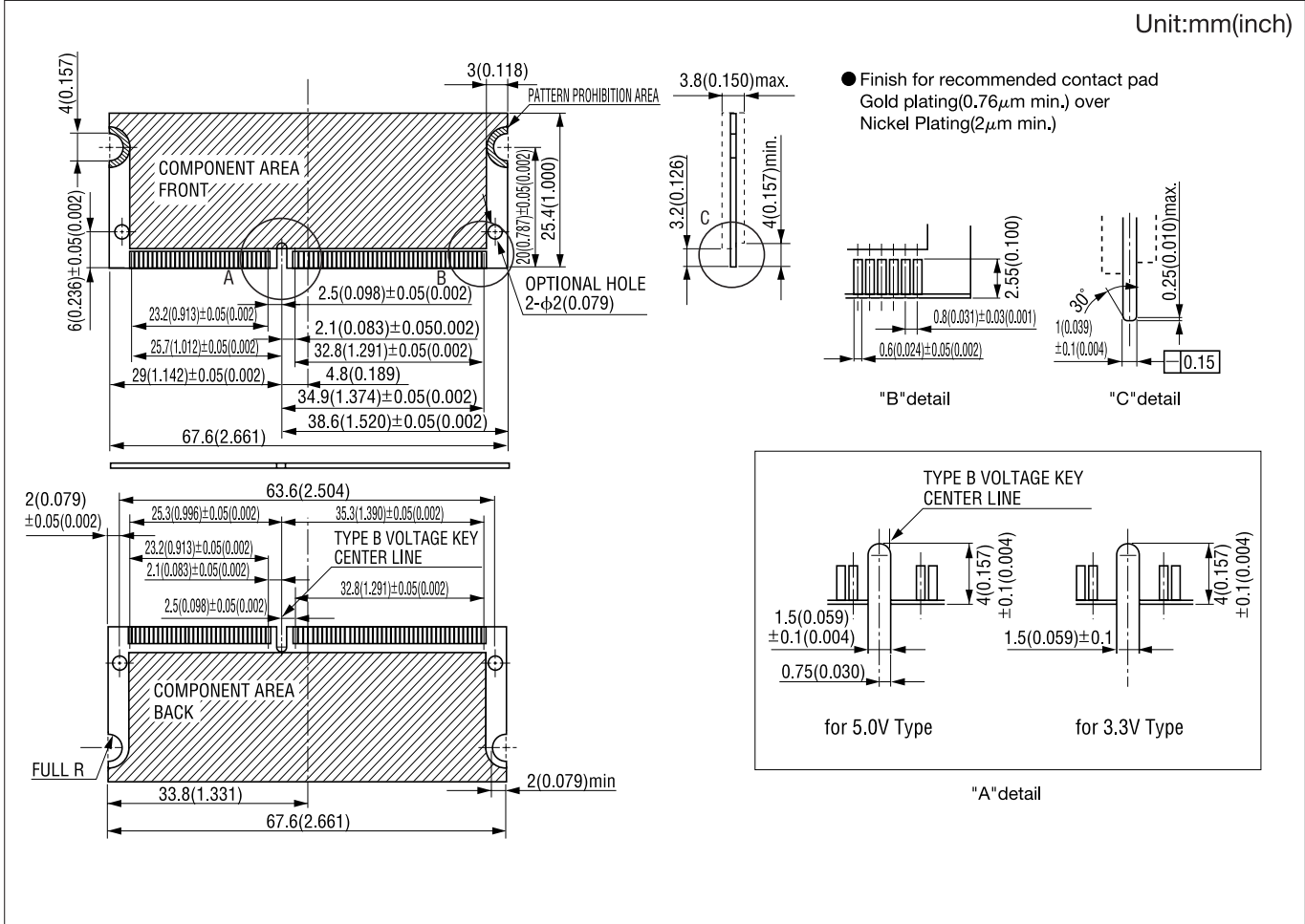
- Insulator : LCP UL94V-0
- Contact : Phosphor Bronze
- Plating : Contact area ; Gold over Nickel
Terminal area ; Gold over Nickel
- Latch material : Copper alloy
- Latch plating : Tin copper over Nickel
- Current rating : 0.5A per contact
- Contact resistance : 50mΩ max
- Withstanding voltage : 250V AC for 1 minute
- Insulation resistance : 500MΩ min. at 250V DC
- Temperature : -55°C to +85°C

ORDER CODE

DM **-144** **-F**

- Type
1 : For 5.0 Volt
2 : For 3.3 Volt
- Contact plating
B : Gold plating 0,1μm min
- Number of contact
144 : 144pin
- Series name
DM03 : 4.0mm(0.1572") for mounted height
DM04 : 5.2mm(0.205") for mounted height
- **F** : RoHS Compliance

Recommended Memory Module Board Layout

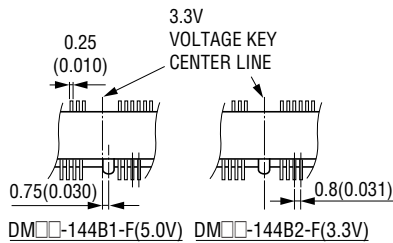
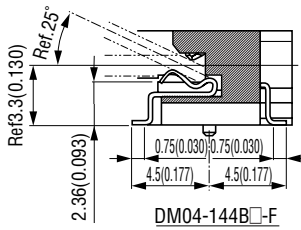
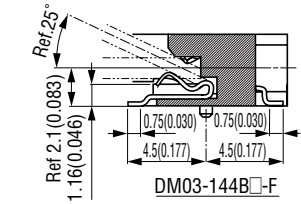


DM□□-144□□-F

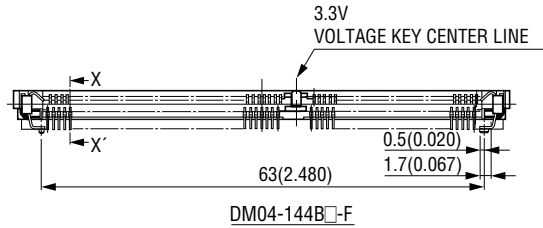
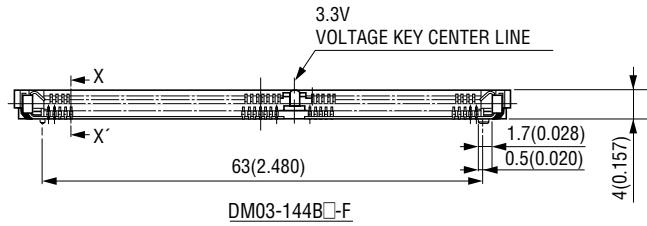
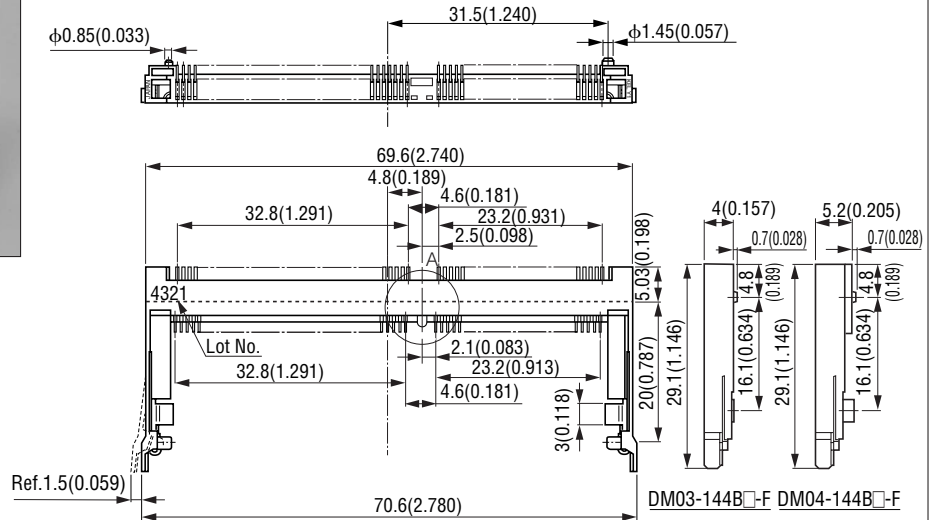
Unit:mm(inch)



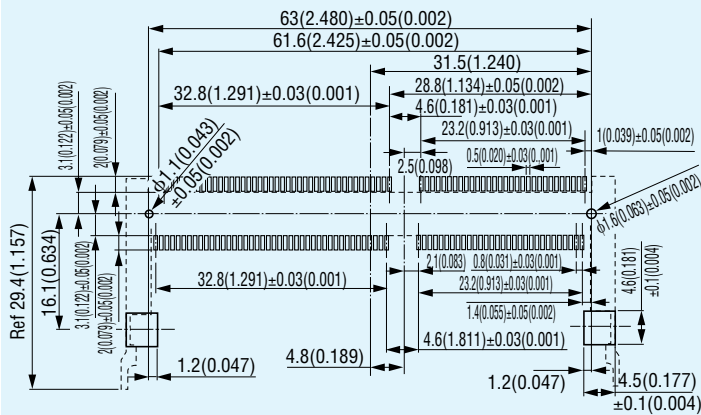
X-X' Cross Section



"A" detail



Recommended PCB Layout
(Component Side View)



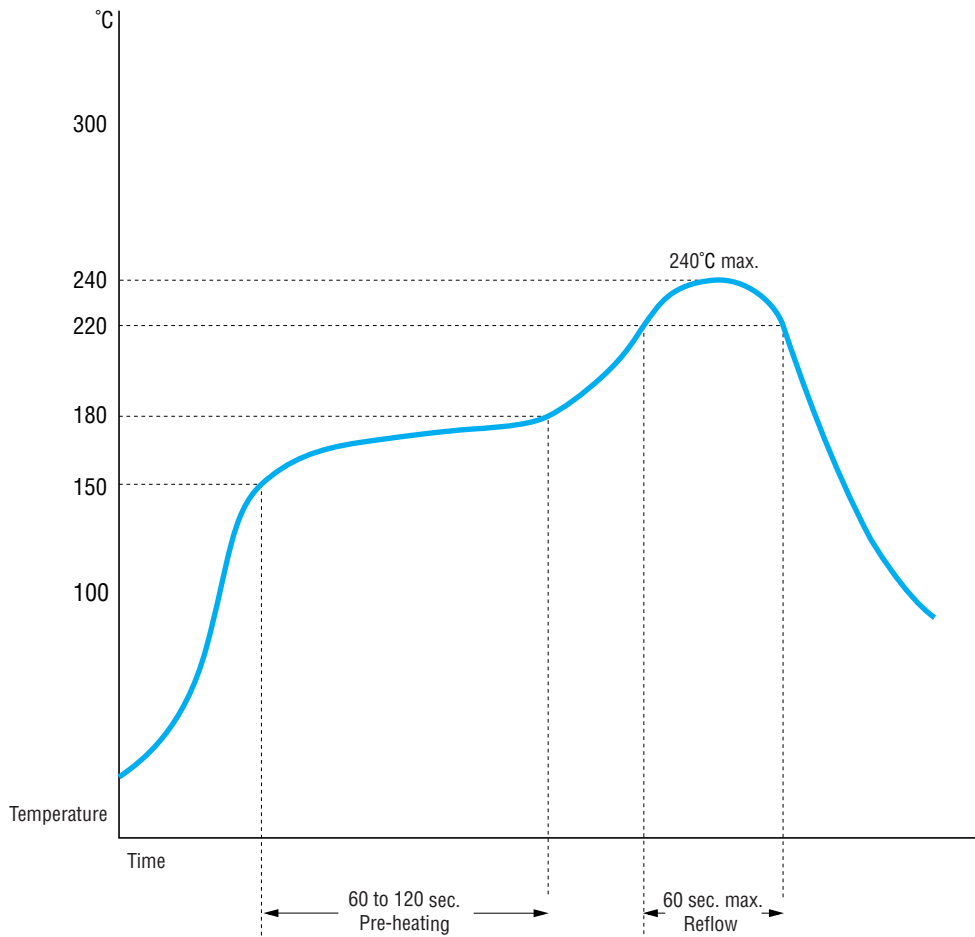
Packaging style
Tray

Product Table

No. of contacts	Part Number	Number of packaging
144	DM03-144B□-F	20
144	DM04-144B□-F	20

Recommended Soldering Conditions (SMT type)

- Soldering Iron : 300°C or lower, 3 sec. max.
- Solder flux should be applied to PCB and not to contact tails.
- Recommended stencil thickness for solder paste is 0.15mm (0.006")
- Recommended temperature profile for IR reflow as the follows:



Note: Flux should be applied to PCB not connector tails.